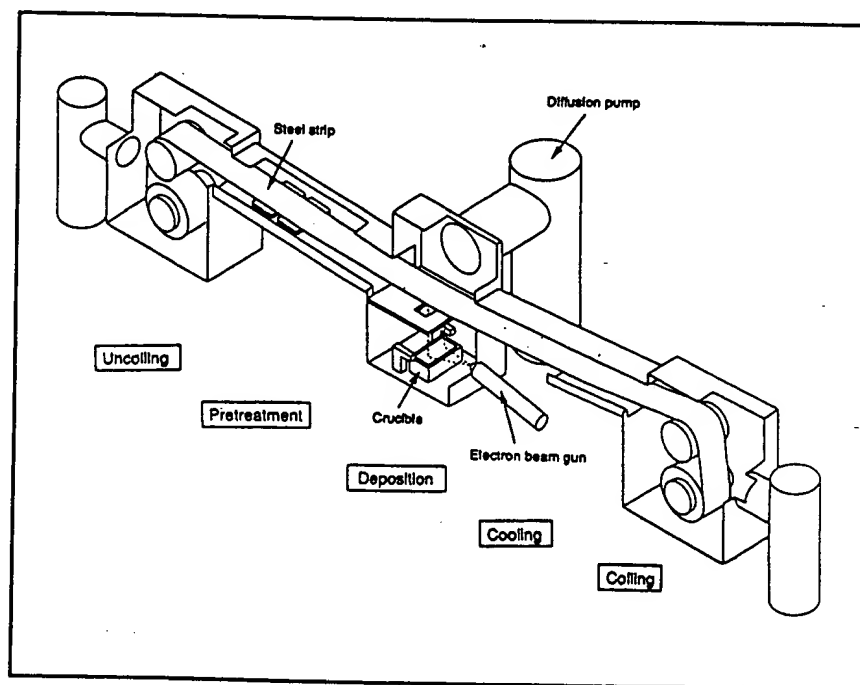


HANDBOOK OF DEPOSITION TECHNOLOGIES FOR FILMS AND COATINGS

Science, Technology
and Applications

Second Edition



Edited by
Rointan F. Bunshah

NOYES PUBLICATIONS

Appendix C

Goldwasser *et al.*
Application No.: 08/847,967

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Appendix C

Goldwasser *et al.*

Application No.: 08/847,967

Contents

1	Deposition Technologies: An Overview	1
	<i>Rointan F. Bunshah</i>	
1.0	THE MARKET	1
2.0	INTRODUCTION	2
3.0	AIM AND SCOPE	4
4.0	DEFINITIONS AND CONCEPTS	5
5.0	PHYSICAL VAPOR DEPOSITION (PVD) PROCESS TERMINOLOGY	6
6.0	CLASSIFICATION OF COATING PROCESSES	8
7.0	GAS JET DEPOSITION WITH NANO-PARTICLES	10
8.0	MICROSTRUCTURE AND PROPERTIES	12
9.0	UNIQUE FEATURES OF DEPOSITED MATERIALS AND GAPS IN UNDERSTANDING	14
10.0	CURRENT APPLICATIONS	15
10.1	Decorative/Functional Coating	15
10.2	High Temperature Corrosion	16
10.3	Environmental Corrosion	16
10.4	Friction and Wear	16
10.5	Materials Conservation	17
10.6	Cutting Tools	17
10.7	Nuclear Fuels	18
10.8	Biomedical Uses	18
10.9	Electrical Uses	18

xvi Contents

11.0 "FRONTIER AREAS" FOR THE APPLICATION OF THE PRODUCTS OF DEPOSITION TECHNOLOGY	18
12.0 SELECTION CRITERIA	20
13.0 SUMMARY	22
APPENDIX 1: DEPOSITION PROCESS DEFINITIONS	23
Conduction and Diffusion Processes	23
Chemical processes	24
Wetting Process	24
Spraying Processes	25
REFERENCES	28

2 Plasmas in Deposition Processes29

John A. Thornton and Joseph E. Greene

1.0 INTRODUCTION	29
2.0 PARTICLE MOTION	30
2.1 Mean Free Path and Collision Cross Sections	30
2.2 Free Electron Kinetic Energy in a Plasma	32
2.3 Electron Energy Distribution Functions	33
2.4 Collision Frequencies	35
3.0 COLLECTIVE PHENOMENA	42
3.1 Plasma Sheaths	43
3.2 Ambipolar Diffusion	48
3.3 Plasma Oscillations	49
4.0 PLASMA DISCHARGES	50
4.1 Introduction	50
4.2 Ionization Balances and the Paschen Relation	51
4.3 Cold Cathode Discharges	56
4.4 Magnetron Discharges	58
4.5 RF Discharges	59
5.0 PLASMA VOLUME REACTIONS	61
5.1 Introduction	61
5.2 Electron/Atom Interactions	61
5.3 Electron/Molecule Interactions	62
5.4 Metastable Species	64
5.5 Applications of Volume Reactions	66
6.0 SURFACE REACTIONS	67
6.1 Introduction	67
6.2 Ion Bombardment	67
6.3 Electron Bombardment	74
6.4 Glow Discharge Surface Cleaning and Activation	74
REFERENCES	77

Appendix C

Goldwasser *et al.*

Application No.: 08/847,967

3	Surface Preparation for Film and Coating Deposition Processes	82
	<i>Donald M. Mattox</i>	
1.0	INTRODUCTION	82
2.0	CONTAMINATION	84
2.1	Recontamination	85
3.0	ENVIRONMENT CONTROL	87
4.0	CLEANING PROCESSES	93
4.1	Particulate Removal	94
4.2	Abrasive Cleaning	95
4.3	Etch Cleaning	95
4.4	Fluxing	96
4.5	Alkaline Cleaners	96
4.6	Detergent Cleaning	96
4.7	Chelating Agents	97
4.8	Solvent Cleaning	97
4.9	Oxidation Cleaning	102
4.10	Volatilization Cleaning	104
4.11	Hydrogen Reduction Cleaning	104
4.12	Electrolytic Cleaning	105
5.0	DRYING AND OUTGASSING	106
6.0	MONITORING OF CLEANING	107
7.0	IN SITU CLEANING	108
7.1	Ion Scrubbing	108
8.0	PLASMAS	108
8.1	Generation of Plasmas	109
8.2	Plasma Chemistry	114
8.3	Bombardment Effects on Surfaces	115
8.4	Sputter Cleaning and Etching	117
9.0	STORAGE AND HANDLING	121
10.0	ACTIVATION AND SENSITIZATION	122
11.0	SURFACE MODIFICATION	124
12.0	PASSIVATION AND PRESERVATION	125
13.0	SAFETY	126
	REFERENCES	126
4	Evaporation: Processes, Bulk Microstructures and Mechanical Properties	131
	<i>Rointan F. Bunshah</i>	
1.0	GENERAL INTRODUCTION	131
2.0	SCOPE	133

Appendix C

xviii Contents

HA
DE
FO
Sec
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L
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C
i

3.0	PVD PROCESSES	133
3.1	Preamble	133
3.2	PVD Processes	134
3.3	Advantages and Limitations	139
4.0	THEORY AND MECHANISMS	140
4.1	Vacuum Evaporation	140
5.0	EVAPORATION PROCESS AND APPARATUS	143
5.1	The System	143
6.0	EVAPORATION SOURCES	146
6.1	General Considerations	146
6.2	Resistance Heated Sources	149
6.3	Sublimation Sources	150
6.4	Evaporation Source Materials	152
6.5	Induction Heated Sources	154
6.6	Electron Beam Heated Sources	155
6.7	Arc Evaporation	163
7.0	LASER INDUCED EVAPORATION/LASER ABLATION/ PULSED LASER DEPOSITION (PLD)	166
8.0	DEPOSITION RATE MONITORS AND PROCESS CONTROL	168
8.1	Monitoring of the Vapor Stream	168
8.2	Monitoring of Deposited Mass	170
8.3	Monitoring of Specific Film Properties	170
8.4	Evaporation Process Control	173
9.0	DEPOSITION OF VARIOUS MATERIALS	175
9.1	Deposition of Metals and Elemental Semiconductors	175
9.2	Deposition of Alloys	175
9.3	Deposition of Intermetallic Compounds	179
9.4	Deposition of Refractory Compounds	183
9.5	Reactive Evaporation Process	187
9.6	Activated Reactive Evaporation (ARE)	187
9.7	Materials Synthesized by Evaporation-based Processes	197
10.0	MICROSTRUCTURE OF PVD CONDENSATES	198
10.1	Microstructure Evolution	198
10.2	Texture	210
10.3	Residual Stresses	211
10.4	Defects	211
11.0	PHYSICAL PROPERTIES OF THIN FILMS	215
12.0	MECHANICAL AND RELATED PROPERTIES	215
12.1	Mechanical Properties	215
13.0	PURIFICATION OF METALS BY EVAPORATION	230
	APPENDIX	232
	On Progress in Scientific Investigations in the Field of Vacuum Evaporation in the Soviet Union	232
	REFERENCES	235

Appendix C

5	Sputter Deposition Processes	249
	<i>John A. Thornton and Joseph E. Greene</i>	
1.0	INTRODUCTION	249
1.1	Sputter Deposition Systems	252
1.2	Sputter-Deposition Applications	253
1.3	Process Implementation	256
1.4	History of Sputter Deposition and Background Reading ..	257
2.0	SPUTTERING MECHANISMS	258
2.1	Sputtering Rate	259
2.2	Momentum Exchange	263
2.3	Alloys and Compounds	266
2.4	Sputtering with Reactive Species	269
2.5	The Nature of Sputtered Species	270
2.6	Energy Distribution of Sputtered Species	272
3.0	SPUTTER DEPOSITION TECHNIQUES	275
3.1	Planar Diode and the DC Glow Discharge	275
3.2	Triode Discharge Devices	279
3.3	Magnetrons	280
3.4	RF Sputtering	292
3.5	Ion-Beam Sputtering	301
4.0	SPUTTER DEPOSITION MODES	302
4.1	Reactive Sputtering	302
4.2	Bias Sputtering	306
	REFERENCES	311
6	Ion Plating	320
	<i>Donald M. Mattox</i>	
1.0	INTRODUCTION	320
2.0	PROCESSING PLASMA	325
3.0	GENERATION OF PLASMAS	325
3.1	DC Diode Discharge	325
3.2	RF Discharge	329
3.3	Microwave Discharges	330
3.4	Electron Emitter Discharge	330
3.5	Magnetron Discharges	331
3.6	Plasma Enhancement	332
4.0	PLASMA CHEMISTRY	333
5.0	BOMBARDMENT EFFECTS ON SURFACES	334
5.1	Collisional Effects	337
5.2	Surface Region Effects	342
5.3	Near Surface Region Effects	343
5.4	Bulk Effects	343

Appendix C

F I E S I
v b r u t e n
k f i s p t c
t c p s s c f t s a t a
f i t u a a e a

7	Chemical Vapor Deposition.....	374
	<i>Jan-Otto Carlsson</i>	
1.0	INTRODUCTION	374
2.0	IMPORTANT REACTION ZONES IN CVD	375
3.0	DESIGN OF CVD EXPERIMENTS	376
3.1	Classification of CVD Reactions	377
3.2	Thermodynamics	379
3.3	Adhesion	383

Goldwasser *et al.*
Application No.: 08/847,967

xxii Contents

4.0	MATERIALS DEPOSITED BY REACTIVE VAPOR DEPOSITION PROCESSES	465
5.0	KEY ISSUES IN PLASMA-ASSISTED REACTIVE VAPOR DEPOSITION PROCESSES	466
5.1	Plasma Volume Chemistry	466
5.2	Type and Nature of the Bombardment of the Growing Film	467
6.0	PLASMA-ASSISTED DEPOSITION TECHNIQUES IN CURRENT USAGE	469
6.1	Plasma-Assisted Chemical Vapor Deposition	469
6.2	Sputter Deposition	470
6.3	Activated Reactive Evaporation (ARE)	471
7.0	LIMITATIONS OF CURRENT PLASMA-ASSISTED TECHNIQUES	473
8.0	HYBRID PROCESSES	475
9.0	CONCLUSIONS	475
	REFERENCES	479
10	Deposition from Aqueous Solutions: An Overview	480
	<i>Morton Schwartz</i>	
1.0	INTRODUCTION	480
2.0	GENERAL PRINCIPLES	482
3.0	ELECTRODEPOSITION	494
3.1	Mechanism of Deposition	494
3.2	Parameters	500
4.0	PROCESSING TECHNIQUES	510
5.0	SELECTION OF DEPOSIT	513
5.1	Individual Metals	513
5.2	Alloy Deposition	517
6.0	SELECTED SPECIAL PROCESSES	524
6.1	Electroless Deposition	524
6.2	Electroforming	531
6.3	Anodizing	534
6.4	Plating on Plastics	544
6.5	Plating Printed Circuit Boards	545
7.0	STRUCTURES AND PROPERTIES OF DEPOSITS	548
8.0	SUMMARY	570
	APPENDIX A - Preparation of Substrates for Electroplating	571
	APPENDIX B - Representative Electroless Plating Solution Formulation	573
	APPENDIX C - Comparison of Aluminum Anodizing Processes (Types I, II and III)	576
	REFERENCES	579

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Appendix C

Goldwasser *et al.*

Application No.: 08/847,967

11	Advanced Thermal Spray Deposition Techniques	591
	<i>Robert C. Tucker, Jr.</i>	
1.0	INTRODUCTION	591
2.0	EQUIPMENT AND PROCESSES	592
2.1	Plasma Spray Process	592
2.2	Detonation Gun Deposition Process	600
2.3	High Velocity Oxy-Fuel Deposition	602
2.4	Thermal Control	603
2.5	Auxiliary Equipment	604
2.6	Equipment-Related Coating Limitations	605
3.0	TOTAL COATING PROCESS	606
3.1	Powder	606
3.2	Substrate Preparation	606
3.3	Masking	607
3.4	Coating	607
3.5	Finishing	609
4.0	COATING STRUCTURE AND PROPERTIES	610
4.1	Surface Macrostructure and Microstructure	610
4.2	Microstructure	611
4.3	Bond Strength	617
4.4	Residual Stress	618
4.5	Density	619
4.6	Mechanical Properties	621
4.7	Wear and Friction	627
4.8	Corrosion Properties	634
4.9	Thermal Properties	636
4.10	Electrical Characteristics	638
5.0	SUMMARY	639
	REFERENCES	639
12	Non-Elemental Characterization of Films and Coatings	643
	<i>Donald M. Mattox</i>	
1.0	INTRODUCTION	643
2.0	CHARACTERIZATION	645
3.0	FILM FORMATION	651
4.0	ELEMENTAL AND STRUCTURAL ANALYSIS	655
5.0	SOME PROPERTY MEASUREMENTS	656
5.1	Adhesion	656
5.2	Film Thickness	663
5.3	Film Stress	665

Appendix C

xxiv Contents

5.4	Coefficient of Thermal Expansion	669
5.5	Mechanical Properties	669
5.6	Electrical Resistivity	670
5.7	Temperature Coefficient of Resistivity (TCR)	670
5.8	Electromigration	671
5.9	Density	671
5.10	Porosity	672
5.11	Chemical Etch Rate (Dissolution)	675
6.0	SUMMARY	675
	REFERENCES	676

13 Nucleation, Film Growth, and Microstructural Evolution 681

Joseph E. Greene

1.0	INTRODUCTION	681
2.0	NUCLEATION AND THE EARLY STAGES OF FILM GROWTH	682
2.1	Three-Dimensional Nucleation and Growth	684
2.2	Two-Dimensional Nucleation and Growth	695
2.3	Stranski-Krastanov Nucleation and Growth	702
3.0	COMPUTER SIMULATIONS OF MICROSTRUCTURE EVOLUTION	704
3.1	Film Growth in the Ballistic Aggregation, Low-Adatom Mobility, Limit	706
3.2	Effects of Adatom Migration	708
4.0	MICROSTRUCTURE EVOLUTION AND STRUCTURE-ZONE	710
5.0	EFFECTS OF LOW-ENERGY ION IRRADIATION DURING FILM GROWTH	717
5.1	Effects of Low-Energy Ion/Surface Interactions on Nucleation Kinetics	717
5.2	Effects of Low-Energy Ion/Surface Interactions on Film Growth Kinetics	724
	REFERENCES	734

14 Metallurgical Applications 740

Rointan F. Bunshah

1.0	INTRODUCTION	740
2.0	CORROSION	740
3.0	GALVANIC CORROSION	741
3.1	Galvanic Cells	742
4.0	EMF AND GALVANIC SERIES	744

Appendix C

Goldwasser *et al.*

Application No.: 08/847,967

5.0	COATINGS FOR GALVANIC CORROSION	744
6.0	METHODS OF DEPOSITION OF METALLIC COATINGS	746
7.0	EXAMPLES OF CORROSION-RESISTANT COATINGS	747
7.1	Preamble	747
8.0	HIGH TEMPERATURE OXIDATION/CORROSION	750
9.0	FRICTION AND WEAR	755
9.1	Adhesive Wear	755
9.2	Fretting Wear	755
9.3	Abrasive Wear	756
9.4	Fatigue Wear	756
9.5	Impact Erosion Wear by Solid Particles and Fluids	756
9.6	Corrosive Wear	757
9.7	Electric Arc Induced Wear	757
9.8	Solution Wear (Thermodynamic Wear)	757
10.0	COATINGS TO REDUCE FRICTION AND WEAR	757
10.1	Friction	757
10.2	Lubrication	759
10.3	Wear	759
	REFERENCES	761

15 Characterization of Thin Films and Coatings763

Gary E. McGuire

1.0	INTRODUCTION	763
2.0	SURFACE ANALYSIS TECHNIQUES	763
2.1	Auger Electron Spectroscopy	763
2.2	Photoelectron Spectroscopy	771
2.3	Secondary Ion Mass Spectroscopy	777
2.4	Rutherford Backscattering Spectroscopy	786
3.0	IMAGING ANALYSIS TECHNIQUES	796
3.1	Scanning Electron Microscopy	796
3.2	Transmission Electron Microscopy	802
4.0	OPTICAL ANALYSIS TECHNIQUES	808
4.1	Ellipsometry	808
4.2	Fourier Transform Infrared Spectroscopy	812
4.3	Photoluminescence Spectroscopy	815
	REFERENCES	819

16 Jet Vapor Deposition822

Bret L. Halpern and Jerome J. Schmitt

1.0	INTRODUCTION	822
2.0	PRINCIPLES AND APPARATUS OF JVD	823
3.0	DISCUSSION	827

Appendix C

Goldwasser *et al.*

Application No.: 08/847,967

xxvi C n t e n t s

3.1	Jet Structure, Behavior, and Vapor Transport	827
3.2	Substrate Motion	830
4.0	EXAMPLES OF JVD FILMS AND APPLICATIONS	831
4.1	Cu, Au Multilayer Electrodes; Al, Al ₂ O ₃ Microlaminates. .	831
4.2	PZT: Ferroelectric FRAM Nonvolatile Memories	832
4.3	Electronic Grade Silicon Nitride	833
4.4	Fiber Coating for Composite Materials	833
4.5	Coating of Thermally Sensitive Membranes	834
4.6	"Ceramic Host-Organic Guest" Films	834
4.7	Polymer Deposition: Parylene	835
5.0	SUMMARY	835
	REFERENCES	836
	Index	838

Appendix C

Goldwasser *et al.*

Application No.: 08/847,967